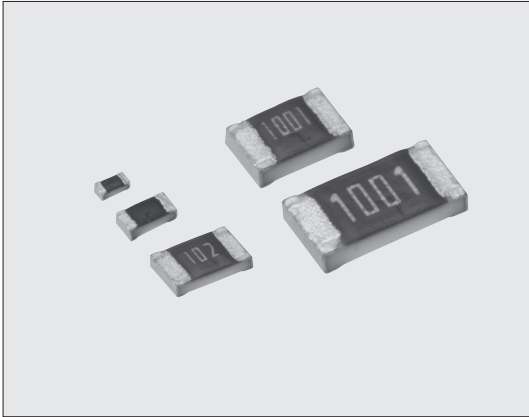


# THICK FILM (ULTRA PRECISION)



## RK73G 矩形片式电阻器 (超精密级) Flat Chip Resistors (Ultra Precision Grade)



外观颜色: 黑色 (1H、1E)、深蓝色 (1J、2A、2B)  
Coating color: Black (1H, 1E), Dark blue (1J, 2A, 2B)

### 特点 Features

- 是表面贴装型的金属釉厚膜电阻器。
- 是阻值允许偏差±0.25%、电阻温度系数±50×10<sup>-6</sup>/K的高精度产品。
- 对应回流焊、波峰焊。
- 端子无铅品,符合欧盟RoHS。电极、电阻膜层、玻璃中所含的铅玻璃不适用欧盟RoHS指令。
- AEC-Q200相关数据已取得。
- Metal-glaze thick film resistor for surface mounting.
- High precision resistor with T.C.R. ±50×10<sup>-6</sup>/K and tolerance ±0.25%.
- Suitable for both flow and reflow solderings.
- Products with lead free termination meet EU-RoHS requirements. EU-RoHS regulation is not intended for Pb-glass contained in electrode, resistor element and glass.
- AEC-Q200 qualified.

### 用途 Applications

- 汽车电子装置、工业设备、工业测量
- 用于替换金属膜片状电阻器。
- Car electronics, Industrial equipment, Industrial measurement
- Replacement of metal film chip resistors.

### 参考标准 Reference Standards

IEC 60115-8  
JIS C 5201-8  
EIAJ RC-2134C

### 额定值 Ratings

型号 Type	额定功率 Power Rating	额定环境温度 Rated Ambient Temp.	额定端子部温度 Rated Terminal Part Temp.	额定端子部温度 T.C.R. (×10 <sup>-6</sup> /K)	电阻值范围 Resistance Range (Ω)			最高使用电压 Max. Working Voltage	最高过载电压 Max. Overload Voltage	二次加工和包装数量/卷 Packaging & Q'ty/Reel (pcs)			
					C: ±0.25% E24, E96	D: ±0.5% E24, E96	F: ±1% E24, E96			TC•TCM	TPL•TP	TD	TE
1H	0.05W	70℃	125℃	±50	-	100~1M <sup>*2</sup>	100~1M <sup>*2</sup>	25V	50V	TC :10,000 TCM:15,000	-	-	-
1E	0.1W				-	-	50V	100V	-	TPL:20,000 TP :10,000	-	-	
1J	0.1W				100~1M	10~1M	10~1M	75V	150V	-	TP :10,000	5,000	-
2A	0.125W				-	-	150V	200V	-	-	5,000	4,000	
2B	0.25W				-	-	200V	400V	-	-	5,000	4,000	

使用温度范围 Operating Temperature Range: -55℃~+155℃

额定电压是√额定功率×公称电阻值所算出的值或表中最高使用电压两者中小的值为额定电压。

Rated voltage = √ Power Rating × Resistance value or Max. working voltage, whichever is lower.

跳线片式电阻器请参照RK73Z系列。

For flat chip jumper resistor, please refer to RK73Z series.

\*2 RK73G 1H (D: ±0.5%, F: ±1%) 的公称电阻值为E24。

\*2 The nominal resistance value for RK73G 1H (D: ±0.5%, F: ±1%) is E24.

根据客户的使用状况, 如果不清楚是该使用额定环境温度还是额定端子部温度, 请以额定端子部温度为优先。

详情请参照14~17页的“端子部温度负荷特性曲线的说明”。

If any questions arise whether to use the “Rated Ambient Temperature” or the “Rated Terminal Part Temperature” in your usage conditions, please give priority to the “Rated Terminal Part Temperature”.

For more details, please refer to “Introduction of the derating curves based on the terminal part temperature” in page 14 to 17.

本产品目录中记载的产品规格如有变更, 恕不一一奉告。订购及使用之前, 请仔细阅读规格表的内容。

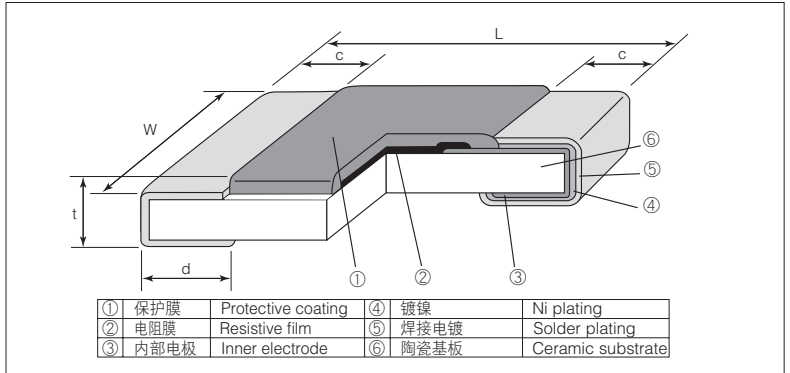
用于车载设备、医疗设备、航空设备以及其他涉及人身安全、或可能引起重大损失的设备上时, 请务必先与我司联系。这些产品在这类用途中出现故障或失灵可能导致人身事故或严重损坏。

Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use.

Contact our sales representatives before you use our products for applications including automobiles, medical equipment and aerospace equipment.

Malfunction or failure of the products in such applications may cause loss of human life or serious damage.

### 结构图 Construction



### 外形尺寸 Dimensions

型号 Type (Inch Size Code)	尺寸 Dimensions (mm)					Weight (g) (1000pcs)
	L	W	c	d	t	
1H (0201)	0.6±0.03	0.3±0.03	0.1±0.05	0.15±0.05	0.23±0.03	0.14
1E (0402)	1.0 <sup>+0.1</sup> <sub>-0.05</sub>	0.5±0.05	0.2±0.1	0.25 <sup>+0.05</sup> <sub>-0.1</sub>	0.35±0.05	0.68
1J (0603)	1.6±0.2	0.8±0.1	0.3±0.1	0.3±0.1	0.45±0.1	2.14
2A (0805)	2.0±0.2	1.25±0.1	0.4±0.2	0.3 <sup>+0.2</sup>	0.5±0.1	4.54
2B (1206)	3.2±0.2	1.6±0.2	0.5±0.3	0.4 <sup>+0.2</sup>	0.6±0.1	9.14

### 品名构成 Type Designation

实例 Example	品种 Product Code	额定功率 Power Rating	端子表面材质 Terminal Surface Material	二次加工 Taping	公称电阻值 Nominal Resistance	阻值允许偏差 Resistance Tolerance
RK73G	2A	1H:0.05W 1E:0.1W 1J:0.1W 2A:0.125W 2B:0.25W	T: Sn (L: Sn/Pb*)	TC•TCM:2mm pitch press paper TPL•TP:2mm pitch punch paper TD:4mm pitch punch paper TE:4mm pitch plastic embossed BK: Bulk	1002 4 digits	C:±0.25% D:±0.5% F:±1%

\*1 1H尺寸只对应表面端子材质T。

\*1 With type 1H, only T is available as the terminal surface material.

端子表面材质, 以无铅品为准。

欲知关于此产品含有的环境负荷物质详情(除EU-RoHS以外), 请与我们联系。

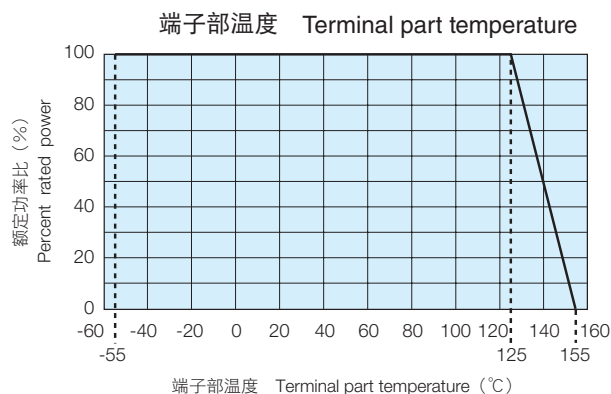
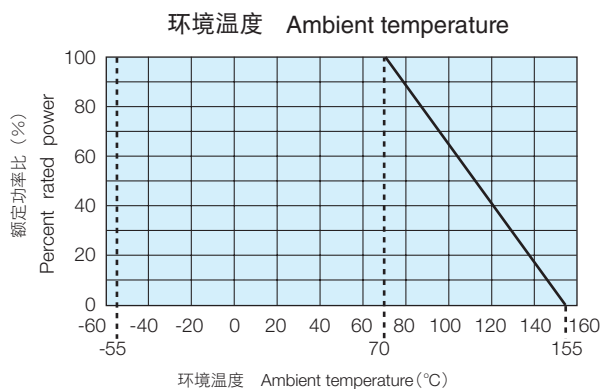
编带细节参照卷末附录C。

The terminal surface material lead free is standard.

Contact us when you have control request for environmental hazardous material other than the substance specified by EU-RoHS.

For further information on taping, please refer to APPENDIX C on the back pages.

## ■ 负荷减轻特性曲线 Derating Curve



在环境温度70℃以上使用时，应按照上图负荷减轻特性曲线，减小额定功率。  
For resistors operated at an ambient temperature of 70°C or above, a power rating shall be derated in accordance with the above derating curve.

超过上述端子部温度使用时，请根据负荷减轻特性曲线减小额定功率后使用。

※关于使用方法，请参照卷首的“端子部温度负荷减轻特性曲线的说明”。

For resistors operated terminal part temperature of described for each size or above, a power rating shall be derated in accordance with derating curve.

※Please refer to “Introduction of the derating curves based on the terminal part temperature” on the beginning of our catalog before use.

## ■ 性能 Performance

试验项目 Test Items	标准值 Performance Requirements $\Delta R \pm (\% + 0.1 \Omega)$		试验方法 Test Methods
	保证值 Limit	代表值 Typical	
电阻值 Resistance	在规定的允许偏差内 Within specified tolerance	-	25°C
电阻温度系数 T.C.R.	在规定值以内 Within specified T.C.R.	-	+25°C/+125°C: 1H +25°C/-55°C and +25°C/+125°C: 1E, 1J, 2A, 2B
过载(短时间) Overload (Short time)	2	0.6	额定电压×2.5倍施加5秒钟 (1E, 2B: 额定电压×2倍) Rated voltage × 2.5 for 5s (1E, 2B: Rated voltage × 2 for 5s)
耐焊接热 Resistance to soldering heat	1	1: 1H 0.4: 1E, 1J, 2A, 2B	260°C ± 5°C, 10s ± 1s
温度突变 Rapid change of temperature	0.5	0.3	-55°C (30min.) / +125°C (30min.) 100 cycles
耐湿负荷 Moisture resistance	3: 1H, 1E 2: 1J, 2A, 2B	1: 1H, 1E 0.6: 1J, 2A, 2B	40°C ± 2°C, 90%~95%RH, 1000h 1.5小时ON、0.5小时OFF的周期 1.5h ON/0.5h OFF cycle
在70°C时的耐久性 Endurance at 70°C	3: 1H, 1E 2: 1J, 2A, 2B	1: 1H, 1E 0.6: 1J, 2A, 2B	70°C ± 2°C, 1000h 1.5小时ON、0.5小时OFF的周期 1.5h ON/0.5h OFF cycle
高温放置 High temperature exposure	1	0.6	+155°C, 1000h

## ■ 使用注意事项 Precautions for Use

- 片状电阻器的基材是氧化铝。由于和安装基板的热膨胀系数不同，在反复施加提供热循环等热应力时，接合部的焊锡（焊缝部）有时会发生裂纹。如果环境温度反复发生很大的变动，并且载荷反复进行ON/OFF，则需要注意龟裂的发生。因热应力而发生的龟裂，取决于所安装的焊盘的大小、焊锡量、安装基板的散热性等，因此在环境温度有很大的变化或载荷ON/OFF的条件下使用时，请充分注意以进行设计。
- The substrate of chip resistors is alumina. Cracks may occur at the connection of solder (solder fillet portion) due to the difference of the coefficient of thermal expansion from a mounting board when heat stress like heat cycle, etc. are repeatedly given to them. Care should be taken to the occurrence of the cracks when the change in ambient temperature or ON/OFF of load is repeated. The occurrence of the crack by heat stress may be influenced by the size of a pad, solder volume, heat radiation of mounting board etc., so please pay careful attention to designing when a big change in ambient temperature and conditions for use like ON/OFF of load can be assumed.